Application/Control No. O9/928,975 Applicant(s)/Patent Under Reexamination HERNER ET AL. Examiner Thomas J. Magee Applicant(s)/Patent Under Reexamination HERNER ET AL. Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-2002/0045342 A1	04-2002	Yongjun Hu et al.	438/656
	В	US-			
	C	US-			
	D	US-			
	Е	US-			
	F	US-			
	G	US-			
	Н	US-			
	1	US-			
	J	US-			
	к	US-			
	L	US-			
	М	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	0					
	P					
	Q					
	R					
	s					
	Т					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Syd R. Wilson, Clarence J. Tracy, and John L. Freeman, Jr., "Handbook of Multilevel Metallization for Integrated Circuits," Noyes Publ., Westwood, New Jersey, (1993), pp.44-50.
	V	
	w	
	х	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.